

SiGe:C NPN RF bipolar transistor









Product description

The BFP740 is a wideband NPN RF heterojunction bipolar transistor (HBT).



Feature list

- Low noise figure NF_{min} = 0.85 dB at 5.5 GHz, 3 V, 6 mA
- High gain G_{ms} = 19.5 dB at 5.5 GHz, 3 V, 15 mA
- $OIP_3 = 24.5 \text{ dBm at } 5.5 \text{ GHz}, 3 \text{ V}, 15 \text{ mA}$

Product validation

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

Potential applications

- Wireless communications: WLAN, WiMax and UWB
- Satellite communication systems: GNSS navigation systems (GPS, GLONASS, BeiDou, Galileo), satellite radio (SDARs, DAB) and C-band LNB
- Multimedia applications such as portable TV, CATV and FM radio
- ISM applications like RKE, AMR and Zigbee, as well as for emerging wireless applications

Device information

Table 1 Part information

Product name / Ordering code	Package	Pin Configuration				Marking	Pieces / Reel
BFP740 / BFP740H6327XTSA1	SOT343	1 = B	2 = E	3 = C	4 = E	R7s	3000

Attention: ESD (Electrostatic discharge) sensitive device, observe handling precautions

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Absolute maximum ratings

Absolute maximum ratings 1

Table 2 Absolute maximum ratings at $T_A = 25$ °C (unless otherwise specified)

Parameter	Symbol	Symbol Values			Note or test condition	
		Min.	Max.			
Collector emitter voltage	V_{CEO}	_	4.0	V	Open base	
			3.5		T _A = -55 °C, open base	
Collector emitter voltage	V_{CES}		13		E-B short circuited	
Collector base voltage	V_{CBO}		13		Open emitter	
Emitter base voltage	V_{EBO}		1.2		Open collector	
Base current	I _B		4	mA	_	
Collector current	I _C		45			
Total power dissipation ¹⁾	P _{tot}		160	mW	<i>T</i> _S ≤ 100 °C	
Junction temperature	TJ		150	°C	-	
Storage temperature	T_{Stg}	-55	150			

Attention: Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Exceeding only one of these values may cause irreversible damage to the integrated circuit.

 T_S is the soldering point temperature. T_S is measured on the emitter lead at the soldering point of the PCB.



Thermal characteristics

2 Thermal characteristics

Table 3 Thermal resistance

Parameter	Symbol		Values			Note or test condition
		Min.	Тур.	Max.		
Junction - soldering point	R _{thJS}	_	310	_	K/W	-

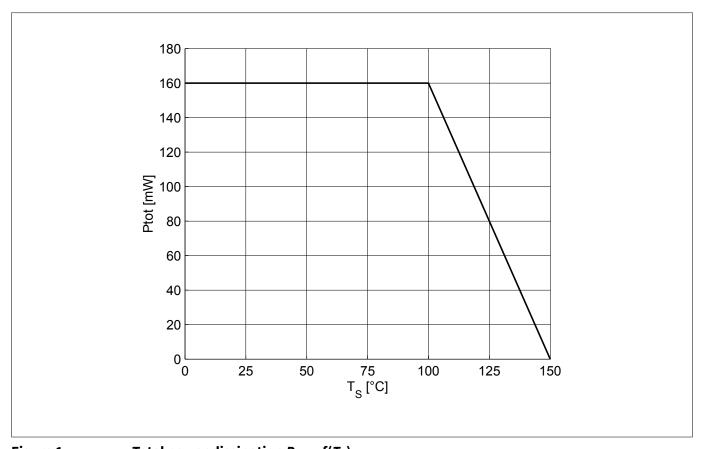


Figure 1 Total power dissipation $P_{\text{tot}} = f(T_S)$

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Electrical characteristics

3 Electrical characteristics

3.1 DC characteristics

Table 4 DC characteristics at $T_A = 25$ °C

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.		
Collector emitter breakdown voltage	V _{(BR)CEO}	4.0	4.7	-	V	$I_C = 1 \text{ mA}, I_B = 0,$ open base
Collector emitter leakage current	I _{CES}	_	1	400 ¹⁾ 40 ¹⁾	nA	$V_{CE} = 13 \text{ V}, V_{BE} = 0$ $V_{CE} = 5 \text{ V}, V_{BE} = 0,$ E-B short circuited
Collector base leakage current	I _{CBO}		1	40 ¹⁾	-	$V_{\text{CB}} = 5 \text{ V}, I_{\text{E}} = 0,$ open emitter
Emitter base leakage current	I _{EBO}		1	40 ¹⁾		$V_{\rm EB}$ = 0.5 V, $I_{\rm C}$ = 0, open collector
DC current gain	h _{FE}	160	250	400	_	$V_{CE} = 3 \text{ V}, I_{C} = 25 \text{ mA},$ pulse measured

3.2 General AC characteristics

Table 5 General AC characteristics at $T_A = 25$ °C

Parameter	Symbol	mbol Values				Note or test condition
		Min.	Тур.	Max.		
Transition frequency	f_{T}	_	44	_	GHz	$V_{CE} = 3 \text{ V}, I_{C} = 25 \text{ mA},$ f = 2 GHz
Collector base capacitance	ССВ		0.08		pF	$V_{CB} = 3 \text{ V}, V_{BE} = 0,$ f = 1 MHz, emitter grounded
Collector emitter capacitance	C _{CE}		0.35			$V_{CE} = 3 \text{ V}, V_{BE} = 0,$ f = 1 MHz, base grounded
Emitter base capacitance	СЕВ		0.45			$V_{\text{EB}} = 0.5 \text{ V}, V_{\text{CB}} = 0,$ f = 1 MHz, collector grounded

¹ Maximum values not limited by the device but by the short cycle time of the 100% test

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3.3 Frequency dependent AC characteristics

Measurement setup is a test fixture with Bias-T's in a 50 Ω system, $T_{\rm A}$ = 25 °C.

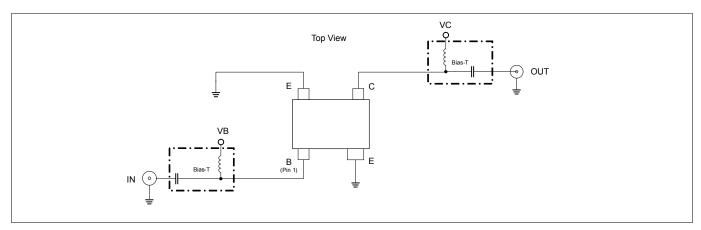


Figure 2 Testing circuit

Table 6 AC characteristics, $V_{CE} = 3 \text{ V}, f = 450 \text{ MHz}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.		
Power gain					dB	
 Maximum power gain 	G _{ms}	-	31.5	_		$I_{\rm C} = 15 {\rm mA}$
 Transducer gain 	$ S_{21} ^2$		28.5			
Noise figure						
 Minimum noise figure 	NF _{min}		0.45			$I_{\rm C}$ = 6 mA
 Associated gain 	G _{ass}		26			
Linearity					dBm	$Z_{\rm S} = Z_{\rm L} = 50 \Omega$
 3rd order intercept point at output 	OIP ₃		22			$Z_{S} = Z_{L} = 50 \Omega$ $I_{C} = 15 \text{ mA}$
• 1 dB gain compression point at output	OP _{1dB}		6.5			

Table 7 AC characteristics, $V_{CE} = 3 \text{ V}, f = 900 \text{ MHz}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.	1	
Power gain					dB	
 Maximum power gain 	G _{ms}	_	28	_		$I_{\rm C} = 15 {\rm mA}$
Transducer gain	$ S_{21} ^2$		27			
Noise figure				1		
 Minimum noise figure 	NF _{min}		0.45			$I_{\rm C}$ = 6 mA
 Associated gain 	G _{ass}		24.5			
Linearity				1	dBm	$Z_{\rm S} = Z_{\rm L} = 50 \Omega$
 3rd order intercept point at output 	OIP ₃		22.5			$Z_{S} = Z_{L} = 50 \Omega$ $I_{C} = 15 \text{ mA}$
• 1 dB gain compression point at output	OP _{1dB}		8			

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Table 8 AC characteristics, $V_{CE} = 3 \text{ V}, f = 1.5 \text{ GHz}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.		
Power gain					dB	
 Maximum power gain 	G _{ms}	_	26	_		$I_{\rm C} = 15 {\rm mA}$
 Transducer gain 	$ S_{21} ^2$		25			
Noise figure						
 Minimum noise figure 	NF _{min}		0.5			$I_{\rm C} = 6 \text{mA}$
 Associated gain 	G _{ass}		22.5			
Linearity					dBm	$Z_{\rm S} = Z_{\rm L} = 50 \ \Omega$
 3rd order intercept point at output 	OIP ₃		23			$Z_{S} = Z_{L} = 50 \Omega$ $I_{C} = 15 \text{ mA}$
• 1 dB gain compression point at output	OP _{1dB}		7			

Table 9 AC characteristics, $V_{CE} = 3 \text{ V}, f = 1.9 \text{ GHz}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.		
Power gain					dB	
 Maximum power gain 	G _{ms}	_	25	_		$I_{\rm C} = 15 {\rm mA}$
 Transducer gain 	$ S_{21} ^2$		23.5			
Noise figure						
 Minimum noise figure 	<i>NF</i> _{min}		0.5			$I_{\rm C} = 6 \text{mA}$
 Associated gain 	G _{ass}		21.5			
Linearity		1			dBm	$Z_{\rm S} = Z_{\rm L} = 50 \Omega$
 3rd order intercept point at output 	OIP ₃		24.5			$Z_{S} = Z_{L} = 50 \Omega$ $I_{C} = 15 \text{ mA}$
• 1 dB gain compression point at output	OP _{1dB}		9			

Table 10 AC characteristics, $V_{CE} = 3 \text{ V}$, f = 2.4 GHz

Parameter	Symbol		Values	Values		Note or test condition	
		Min.	Тур.	Мах.			
Power gain					dB		
Maximum power gain	G _{ms}	_	24	_		I _C = 15 mA	
Transducer gain	$ S_{21} ^2$		22				
Noise figure							
 Minimum noise figure 	NF _{min}		0.55			$I_{\rm C}$ = 6 mA	
 Associated gain 	G _{ass}		20				
Linearity					dBm	$Z_{\rm S} = Z_{\rm L} = 50 \ \Omega$	
 3rd order intercept point at output 	OIP ₃		24.5			$Z_{S} = Z_{L} = 50 \Omega$ $I_{C} = 15 \text{ mA}$	
• 1 dB gain compression point at output	OP _{1dB}		8				

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Electrical characteristics

Table 11 AC characteristics, $V_{CE} = 3 \text{ V}$, f = 3.5 GHz

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.		
Power gain					dB	
 Maximum power gain 	G _{ms}	_	22	_		/ _C = 15 mA
 Transducer gain 	$ S_{21} ^2$		19			
Noise figure						
 Minimum noise figure 	NF _{min}		0.65			$I_{\rm C}$ = 6 mA
 Associated gain 	G _{ass}		17			
Linearity					dBm	$Z_{\rm S} = Z_{\rm L} = 50 \ \Omega$
 3rd order intercept point at output 	OIP ₃		25.5			$Z_{S} = Z_{L} = 50 \Omega$ $I_{C} = 15 \text{ mA}$
• 1 dB gain compression point at output	OP _{1dB}		9			

Table 12 AC characteristics, $V_{CE} = 3 \text{ V}$, f = 5.5 GHz

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.		
Power gain					dB	
 Maximum power gain 	G _{ms}	_	19.5	_		$I_{\rm C} = 15 {\rm mA}$
 Transducer gain 	$ S_{21} ^2$		15			
Noise figure						
 Minimum noise figure 	NF _{min}		0.85			$I_{\rm C} = 6 \text{mA}$
 Associated gain 	G _{ass}		14			
Linearity		1		1	dBm	$Z_{\rm S} = Z_{\rm L} = 50 \ \Omega$
 3rd order intercept point at output 	OIP ₃		24.5			$Z_{S} = Z_{L} = 50 \Omega$ $I_{C} = 15 \text{ mA}$
• 1 dB gain compression point at output	OP _{1dB}		9			

Note:

 $G_{\rm ms}$ = $IS_{21}/S_{12}I$ for k < 1; $G_{\rm ma}$ = $IS_{21}/S_{12}I$ (k-(k^2 -1) $^{1/2}$) for k > 1. In order to get the NF_{min} values stated in this chapter, the test fixture losses have been subtracted from all measured results. OIP₃ value depends on termination of all intermodulation frequency components. Termination used for this measurement is 50 Ω from 0.2 MHz to 12 GHz.



3.4 Characteristic DC diagrams

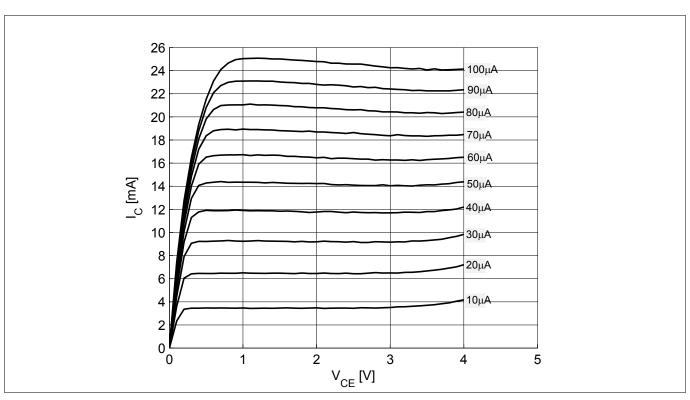


Figure 3 Collector current vs. collector emitter voltage $I_C = f(V_{CE})$, $I_B =$ parameter

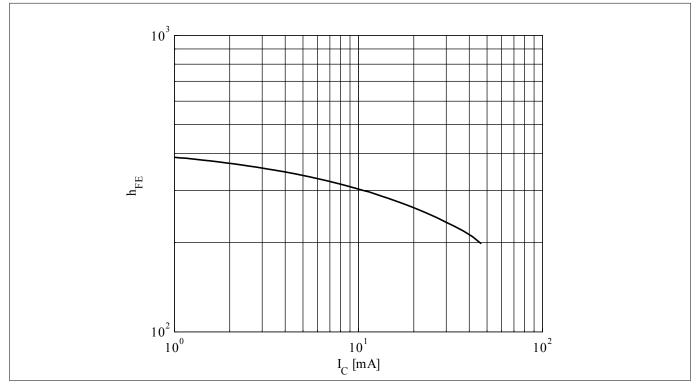


Figure 4 DC current gain $h_{FE} = f(I_C)$, $V_{CE} = 3 \text{ V}$

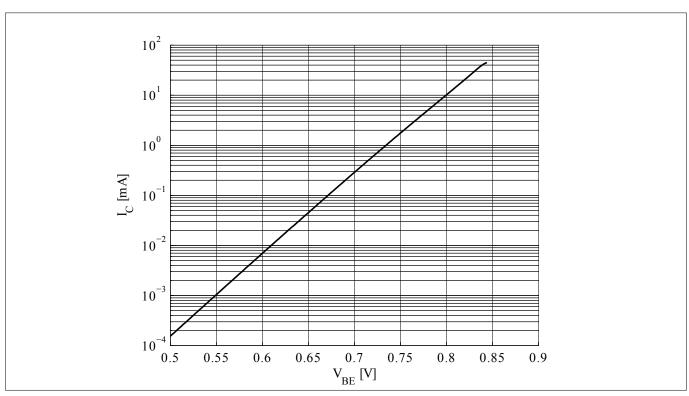


Figure 5 Collector current vs. base emitter forward voltage $I_C = f(V_{BE})$, $V_{CE} = 2 \text{ V}$

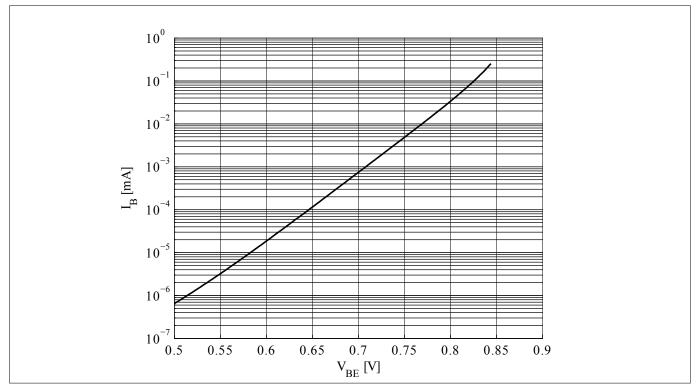


Figure 6 Base current vs. base emitter forward voltage $I_B = f(V_{BE})$, $V_{CE} = 2 \text{ V}$



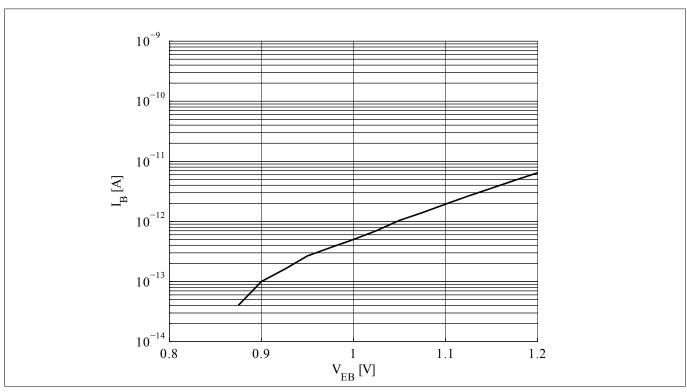


Figure 7 Base current vs. base emitter reverse voltage $I_B = f(V_{EB})$, $V_{CE} = 2 \text{ V}$



3.5 Characteristic AC diagrams

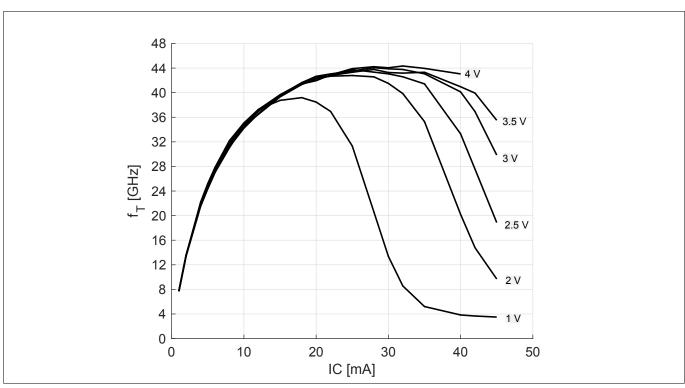


Figure 8 Transition frequency $f_T = f(I_C)$, f = 1 GHz, $V_{CE} =$ parameter

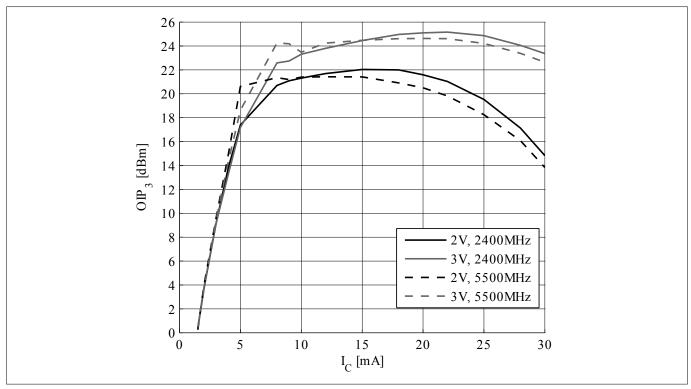


Figure 9 3rd order intercept point $OIP_3 = f(I_C)$, $Z_S = Z_L = 50 \Omega$, V_{CE} , f = parameters

Electrical characteristics

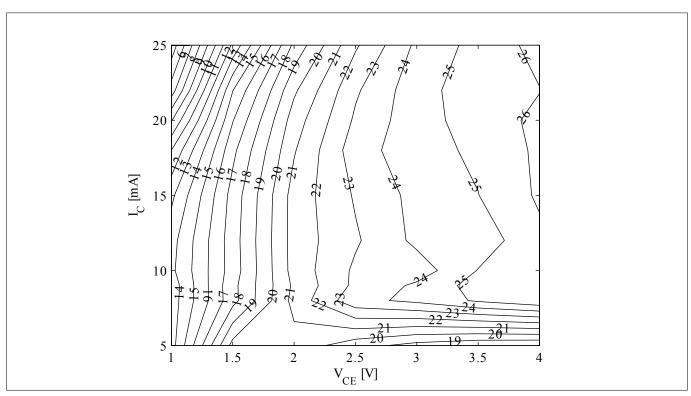


Figure 10 3rd order intercept point at output OIP_3 [dBm] = $f(I_C, V_{CE}), Z_S = Z_L = 50 \Omega, f = 5.5 \text{ GHz}$

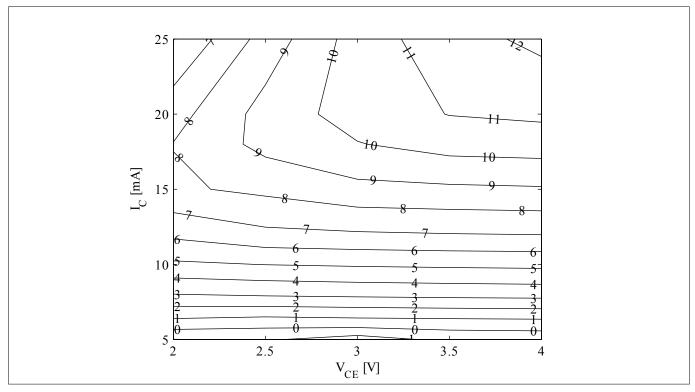


Figure 11 Compression point at output OP_{1dB} [dBm] = $f(I_C, V_{CE}), Z_S = Z_L = 50 \Omega, f = 5.5 \text{ GHz}$

v2.0



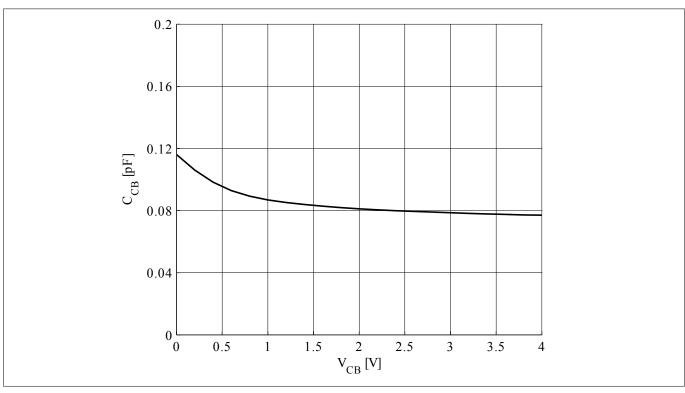
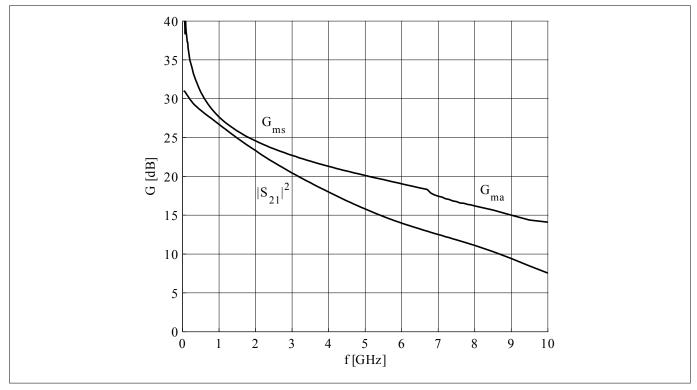


Figure 12 Collector base capacitance $C_{CB} = f(V_{CB}), f = 1 \text{ MHz}$



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Figure 13 Gain G_{ma} , G_{ms} , $IS_{21}I^2 = f(f)$, $V_{CE} = 3 \text{ V}$, $I_C = 15 \text{ mA}$



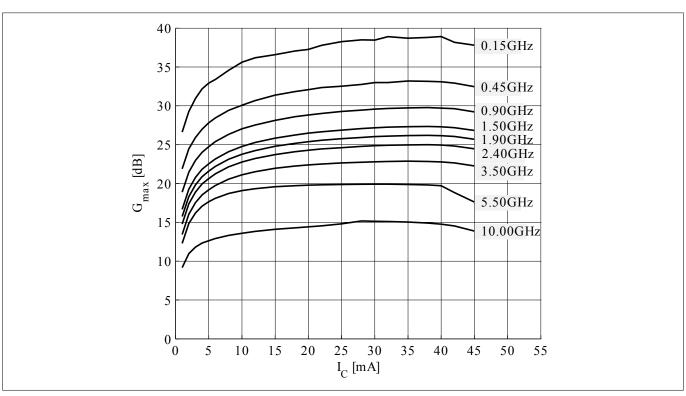


Figure 14 Maximum power gain $G_{\text{max}} = f(I_{\text{C}})$, $V_{\text{CE}} = 3 \text{ V}$, f = parameter in GHz

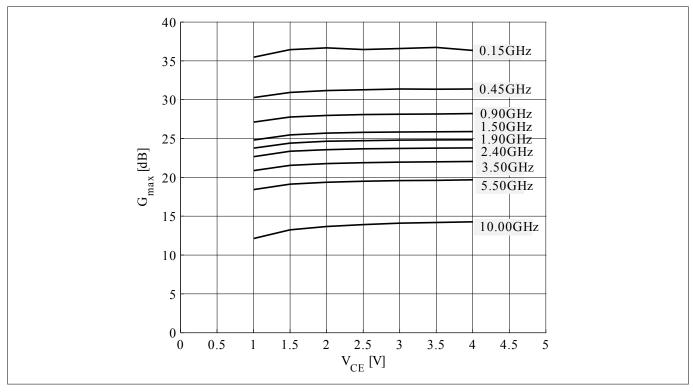


Figure 15 Maximum power gain $G_{\text{max}} = f(V_{\text{CE}})$, $I_{\text{C}} = 15 \text{ mA}$, f = parameter in GHz

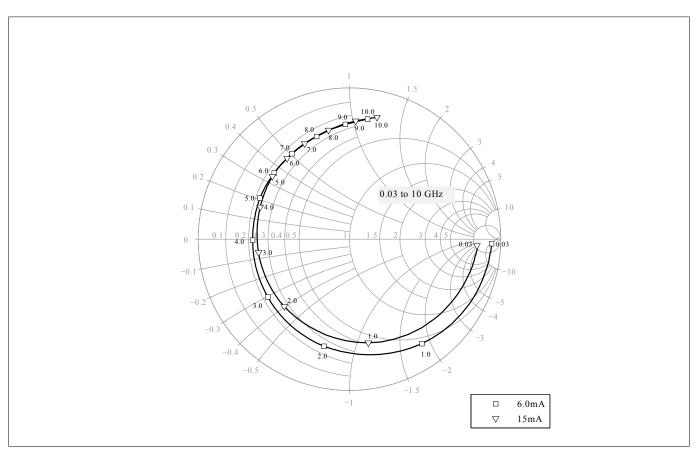


Figure 16 Input reflection coefficient $S_{11} = f(f)$, $V_{CE} = 3 \text{ V}$, $I_C = 6 / 15 \text{ mA}$

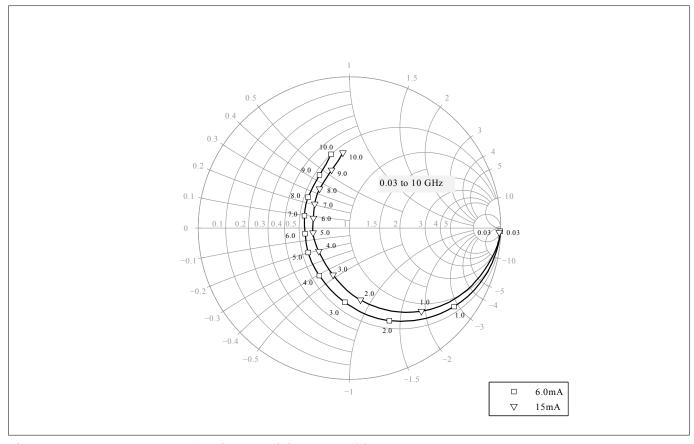


Figure 17 Output reflection coefficient $S_{22} = f(f)$, $V_{CE} = 3 \text{ V}$, $I_C = 6 / 15 \text{ mA}$

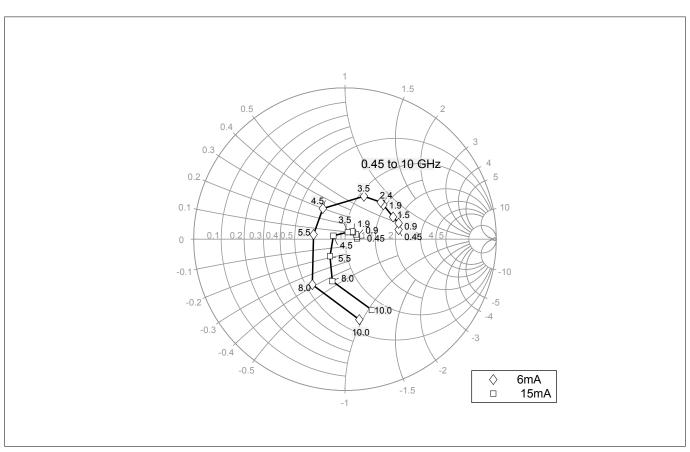


Figure 18 Source impedance for minimum noise figure $Z_{S,opt} = f(f)$, $V_{CE} = 3 \text{ V}$, $I_C = 6 / 15 \text{ mA}$

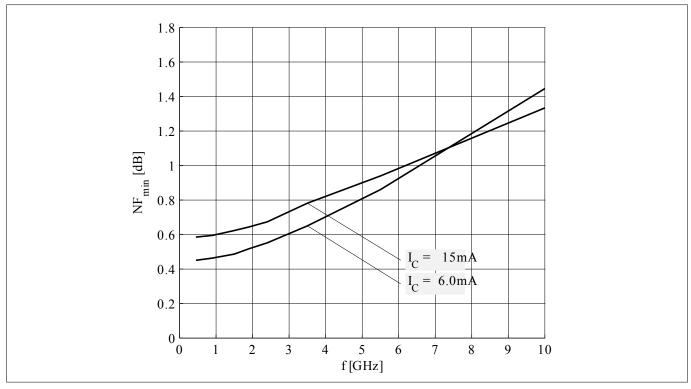


Figure 19 Noise figure $NF_{min} = f(f)$, $V_{CE} = 3 \text{ V}$, $Z_S = Z_{S,opt}$, $I_C = 6 / 15 \text{ mA}$

Electrical characteristics

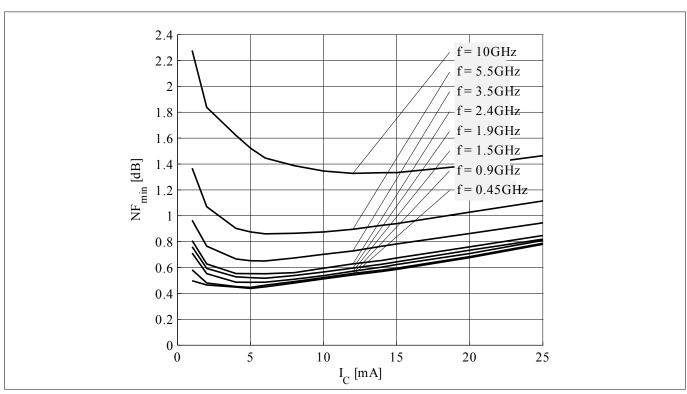


Figure 20 Noise figure $NF_{min} = f(I_C)$, $V_{CE} = 3 \text{ V}$, $Z_S = Z_{S,opt}$, f = parameter in GHz

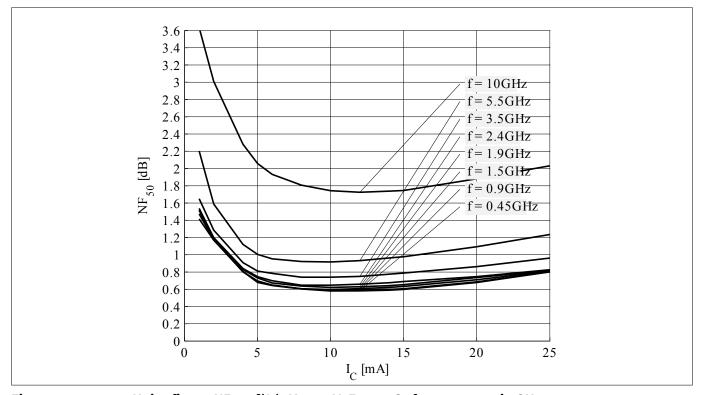


Figure 21 Noise figure $NF_{50} = f(I_C)$, $V_{CE} = 3 \text{ V}$, $Z_S = 50 \Omega$, f = parameter in GHz

Note: The curves shown in this chapter have been generated using typical devices but shall not be considered as a guarantee that all devices have identical characteristic curves, $T_A = 25 \,^{\circ}\text{C}$.



Package information SOT343

Package information SOT343 4

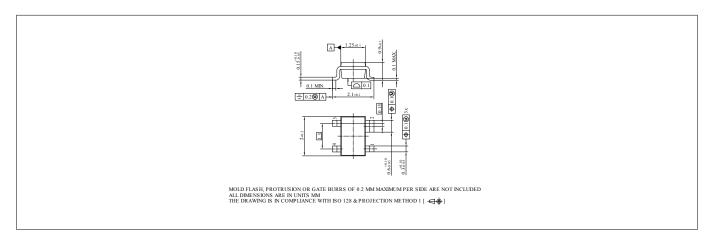


Figure 22 Package outline

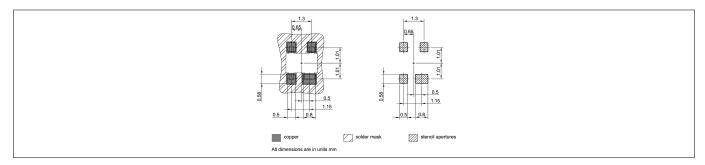


Figure 23 **Foot print**

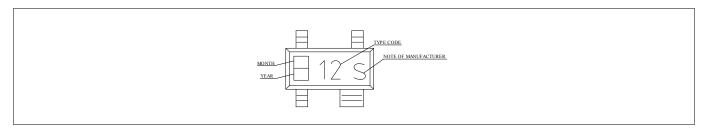


Figure 24 Marking layout example

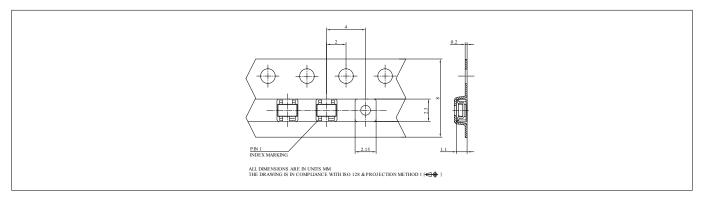


Figure 25 **Tape dimensions**

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Revision history

Revision history

Document version	Date of release	Description of changes
2.0	2018-09-25	New datasheet layout.

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